

L12 ANSWER 1 OF 3 CAPLUS COPYRIGHT 2005 ACS on STN
 AN 2002:105173 CAPLUS
 DN 136:176395
 ED Entered STN: 08 Feb 2002
 TI Manufacture of laminates for printed circuit boards
 IN Shintani, Takashi; Tabata, Haruo; Sasaki, Kimiaki; Ikeda, Kenichi;
 Kawashima, Toshiyuki; Tahara, Shinji
 PA Nitto Denko Corp., Japan
 SO Jpn. Kokai Tokkyo Koho, 6 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 IC ICM H05K003-46
 ICS B29C041-12; B32B015-08; B29K079-00; B29L031-34
 CC 76-2 (Electric Phenomena)
 FAN. CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2002043743	A2	20020208	JP 2000-224455	20000725 <--
PRAI	JP 2000-224455		20000725		

CLASS

	PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
	JP 2002043743	ICM	H05K003-46
		ICS	B29C041-12; B32B015-08; B29K079-00; B29L031-34
AB	Porous resin layers (e.g., polyimides) are formed on metal layers. The resin layers may be formed by wet solidification method. The resin layers have low dielec. constant as well as low dielec. loss.		
ST	polyimide resin laminate printed circuit board		
IT	Dielectric films		
	Printed circuit boards		
	(manufacture of laminates for printed circuit boards)		
IT	Polyimides, uses		
	RL: DEV (Device component use); PNU (Preparation, unclassified); PREP (Preparation); USES (Uses)		
	(manufacture of laminates for printed circuit boards)		
IT	110185-84-7		
	RL: DEV (Device component use); USES (Uses)		
	(manufacture of laminates for printed circuit boards with porous resin layers)		
RN	110185-84-7		

L12 ANSWER 2 OF 3 WPIX COPYRIGHT 2005 THE THOMSON CORP on STN
 AN 2002-446978 [48] WPIX
 DNN N2002-352202 DNC C2002-127450
 TI Laminate for printed circuit substrate, contains porous resin layer formed on metal layer.
 DC A26 A32 A85 L03 P73 U14 V04
 PA (NITL) NITTO DENKO CORP
 CYC 1
 PI JP 2002043743 A 20020208 (200248)* 6 H05K003-46 <--
 ADT JP 2002043743 A JP 2000-224455 20000725
 PRAI JP 2000-224455 20000725
 IC ICM H05K003-46
 ICS B29C041-12
 ICA B32B015-08
 ICI B29K079:00, B29L031:34
 AB JP2002043743 A UPAB: 20020730
 NOVELTY - The laminate for printed circuit substrates, contains a porous resin layer (2) formed on a metal layer (1).
 DETAILED DESCRIPTION - INDEPENDENT CLAIMS are also included for the

following:

(a) Printed circuit substrate;

(b) Manufacturing method of the laminate

USE - For printed circuit substrate (claimed).

ADVANTAGE - The laminate for printed circuit substrate has low dielectric loss and low dielectric constant.

DESCRIPTION OF DRAWING(S) - The figure shows the laminate for printed circuit substrates.

Metal layer 1

Porous resin layer 2

Dwg.3/4

FS CPI EPI GMPI

FA AB; GI

MC CPI: A05-J01B; A12-E07A; L03-H04E3

EPI: U14-H03B1; U14-H04A3; V04-R07A; V04-R07L; V04-R07P

L12 ANSWER 3 OF 3 JAPIO (C) 2005 JPO on STN

AN 2002-043743 JAPIO

TI LAMINATE FOR PRINTED WIRING BOARD AND ITS MANUFACTURING METHOD

IN SHINTANI TAKUJI; TABATA HARUO; SASAKI KIMIMITSU; IKEDA KENICHI; KAWASHIMA TOSHIYUKI; TAWARA SHINJI

PA NITTO DENKO CORP

PI JP 2002043743 A 20020208 Heisei

AI JP 2000-224455 (JP2000224455 Heisei) 20000725

PRAI JP 2000-224455 20000725

SO PATENT ABSTRACTS OF JAPAN (CD-ROM), Unexamined Applications, Vol. 2002

IC ICM H05K003-46

ICS B29C041-12

ICA B32B015-08

ICI B29K079:00, B29L031:34

AB PROBLEM TO BE SOLVED: To provide a laminate for a printed wiring board wherein an insulating layer is permitted and lost in low dielectric.

SOLUTION: A laminated for the printed wiring board, forming a resin porous layer and furthermore a resin film layer on a metal layer, is provided in this invention.

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